



## Atomic Layer Deposition (ALD) Analysis

We have the timely, accurate measurements and information you need to work with atomic layer deposition

Eurofins | EAG Laboratories has been helping product innovators with atomic layer deposition (ALD) support for over 20 years. Our scientists and engineers provide the fast and actionable information you need for ALD development. We explain what the data means, helping to troubleshoot problems and avoid development hurdles.

Eurofins | EAG Laboratories knows that every minute counts. Our experts use the

right techniques from our laboratories' extensive range of instrumentation. Providing customized ALD protocols with ultimate depth resolution, Eurofins | EAG Laboratories can help you meet specifications with on-time and accurate results. From determining composition and detecting contaminants to understanding thin film structures, we support all phases of product development and lifecycle management.

### Eurofins | EAG Laboratories services supporting ALD development

Research & Development	Pilot Process & Ramp Up	Production	Post-Commercialization
Composition	Materials Purity	Process Monitoring	Supplier Material
Contaminants	Composition	Failure Analysis	Verification
Thickness	Tool Matching		Failure Analysis
Uniformity	Process Monitoring		
Density	Failure Analysis		
Roughness			
Thermal Stability			
Crystallinity			
Proprietary protocols for composition, contaminants, phase ID, crystal structure and more	Rush services with same-day and weekend coverage	Process monitoring and validation measurement	Failure analysis at circuit, chip, board and system level

Choosing the right techniques the first time saves you time and money. Eurofins | EAG Laboratories scientists apply these types of analyses and instrumentation for efficient ALD support.

Starting Materials – GDMS, ICP-MS, IGA, GC-MS

Structure Analysis – TEM, AC-STEM, AFM, XRD, EBSD, XRR

Composition Analysis – RBS, XPS, STEM/EDS, Auger, XRF

Contaminant Analysis – SIMS, TOF-SIMS, ICP-MS, GC-MS, TXRF

Thermal Stability – TGA, DSC, DTA, XRD

